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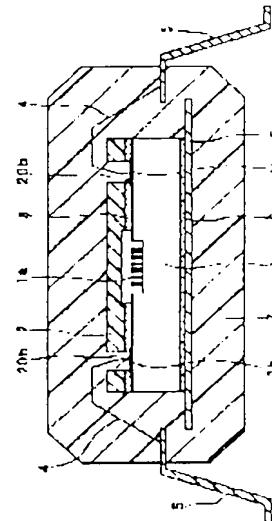
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## (54) SEMICONDUCTOR DEVICE AND MANUFACTURE OF IT

(57) Abstract:

**PROBLEM TO BE SOLVED:** To eliminate the problem caused by intrusion of a cutting water at dicing, related to a semiconductor acceleration sensor comprising a protective cap.

**SOLUTION:** A heat-resistant resin sheet 2 is used as a protective cap which protects a beam structure body 1a formed at a semiconductor chip 1, while the heat-resistant resin sheet 2 is bonded onto the semiconductor chip 1 with a heat-resistant bonding agent 3. A polyimide base material is used as the heat-resistant resin sheet 2 while a silicon adhesive agent is used as the heat-resistant bonding agent 3. The heat-resistant resin sheet 2 is bonded onto the semiconductor chip 1 with the heat-resistant bonding agent 3 like this so that such a problem as intrusion of cutting water is avoided at dicing cut.



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